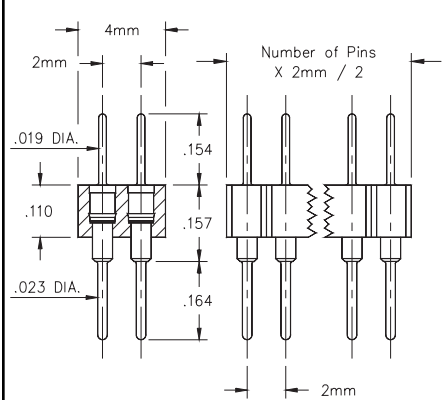


**Fig. 1**

- Series 830 single and double row interconnects have 2mm pin spacing and permit board stacking as low as .322".
- Pin headers (830 & 832 series) use MM #5012 pins. See page 166 for details.
- Sockets (831 & 833 series) use MM #1802 receptacles and accept pin diameters from .015"-.025". See page 138 for details.
- Insulators are high temp. thermoplastic, suitable for all soldering operations.



**Fig. 2**

**Ordering Information**

**Fig. 1**

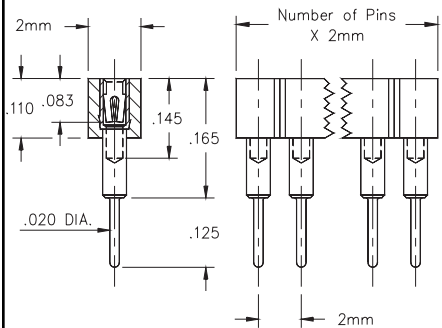
**Single Row Pin Header**

830-XX-0\_\_-10-001000  
Specify # of pins → 01-50

**Fig. 2**

**Double Row Pin Header**

832-XX-\_\_-10-001000  
Specify # of pins → 002-100



**Fig. 3**



*XX= Plating Code See Below*

For RoHS compliance select  $\diamond$  plating code.

SPECIFY PLATING CODE XX=	10 $\diamond$	90	40 $\diamond$	
Pin Plating	10 $\mu$ " Au	200 $\mu$ " Sn/Pb	200 $\mu$ " Sn	

**Fig. 3**

**Single Row Socket**

831-XX-0\_\_-10-001000  
Specify # of pins → 01-50

**Fig. 4**

**Double Row Socket**

833-XX-\_\_-10-001000  
Specify # of pins → 002-100



*XX= Plating Code See Below*

For RoHS compliance select  $\diamond$  plating code.

SPECIFY PLATING CODE XX=	13 $\diamond$	93	43 $\diamond$	
Sleeve (Pin)	10 $\mu$ " Au	200 $\mu$ " Sn/Pb	200 $\mu$ " Sn	
Contact (Clip)	30 $\mu$ " Au	30 $\mu$ " Au	30 $\mu$ " Au	

**Fig. 4**